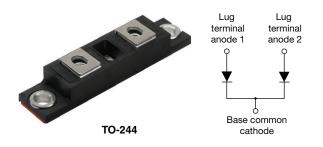
VS-HFA210NJ60CPbF

Vishay Semiconductors

HEXFRED[®] Ultrafast Soft Recovery Diode, 210 A



www.vishay.com

FEATURES

- Very low Q_{rr} and t_{rr}
- UL approved file E222165



please see www.vishay.com/doc?99912

COMPLIANT • Material categorization: for definitions of compliance

RoHS

BENEFITS

- · Reduced RFI and EMI
- Reduced snubbing

DESCRIPTION / APPLICATIONS

HEXFRED® diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems. An extensive characterization of the recovery behavior for different values of current, temperature and dl_F/dt simplifies the calculations of losses in the operating conditions. The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

PRIMARY CHARACTERISTICS				
I _{F(AV)}	210 A			
V _R	600 V			
I _{F(DC)} at T _C	120 A at 100 °C			
Package	TO-244			
Circuit configuration	Two diodes common cathode			

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Cathode to anode voltage	V _R		600	V
Continuous forward current	1	T _C = 25 °C	235	
Continuous forward current	IF	T _C = 100 °C	120	A
Single pulse forward current	I _{FSM}	Limited by junction temperature	600	
Non-repetitive avalanche energy	E _{AS}	L = 100 μ H, duty cycle limited by maximum T _J	2.2	mJ
Maximum power dissipation	Р	T _C = 25 °C	463	w
waximum power dissipation	PD	T _C = 100 °C	185	vv
Operating junction and storage temperature range	T _J , T _{Stg}		-55 to +150	°C

ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25 \text{ °C}$ unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V _{BR}	I _R = 100 μA		600	-	-	
	I _F = 105 A		-	1.38	1.9	V	
Maximum forward voltage	um forward voltage V _{FM}	I _F = 210 A	See fig. 1	-	1.6	2.25	
		I _F = 105 A, T _J = 125 °C		-	1.3	1.56	
Maximum reverse leakage current	I _{RM}	$T_{J} = 125 \ ^{\circ}C, V_{R} = 480 \ V$	See fig. 2	-	1.8	6.0	mA
Junction capacitance	CT	V _R = 200 V	See fig. 3	-	200	300	pF
Series inductance	L _S	From top of terminal hole to mounting plane - 6.0 - n		nH			

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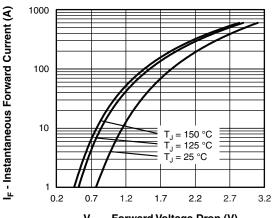
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DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25$ °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNITS		
	t _{rr}	I _F = 1.0 A, dI _F /dt = 200 A/μs, V _R = 30 V		-	35	-			
Reverse recovery time (fig. 5)		T _J = 25 °C		-	90	140	ns		
			T _J = 125 °C		-	160	240		
Deals receivers ourrent (fig. 6)	I _{RRM} -	T _J = 25 °C		-	10	18	٨		
Peak recovery current (fig. 6)		IRRM	T _J = 125 °C	$I_{\rm F} = 105 {\rm A}$	-	15	30	A	
Reverse recovery charge (fig. 7)	. 7) Q _{rr}	$Q_{rr} \qquad \frac{T_{J} = 25 \ ^{\circ}C}{T_{J} = 125 \ ^{\circ}C} \qquad \qquad dI_{F}/dt = 200 \ A/\mu s \\ V_{R} = 200 \ V$	Q _{rr}	T _J = 25 °C		-	450	1300	nC
Reverse recovery charge (lig. 7)				-	1200	3600	no		
	di /dt	T _J = 25 °C		-	310	-	A/µs		
Peak rate of recovery current (fig. 8)	dl _{(rec)M} /dt	T _J = 125 °C		-	240	-	γγµs		

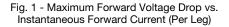
THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	
Maximum junction and storage temperature range	T _J , T _{Stg}	-55	-	150	°C	
Thermal registered, junction to page	Р	-	-	0.27	°C/W K/W	
Thermal resistance, junction to case per module	R _{thJC}	-	-	0.135		
Typical thermal resistance, case to heatsink	R _{thCS}	-	0.10	-	10.00	
Weight		-	68	-	g	
weight		-	2.4	-	oz.	
Mounting torque ⁽¹⁾		30 (3.4)	-	40 (4.6)		
Mounting torque center hole		12 (1.4)	-	18 (2.1)	lbf · in (N · m)	
Terminal torque		30 (3.4)	-	40 (4.6)	(11 11)	
Vertical pull		-	-	80	llaf in	
2" lever pull		-	-	35	lbf ⋅ in	

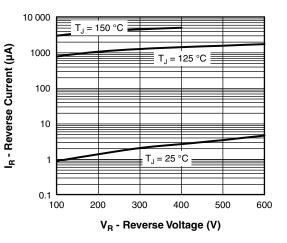
Note

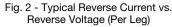
(1) Mounting surface must be smooth, flat, free of burrs or other protrusions. Apply a thin even film or thermal grease to mounting surface. Gradually tighten each mounting bolt in 5 to 10 lbf · in steps until desired or maximum torque limits are reached



V_{FM} - Forward Voltage Drop (V)





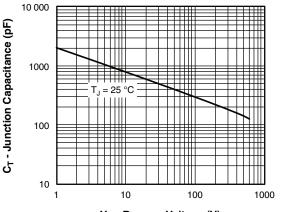


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V_R - Reverse Voltage (V)

Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

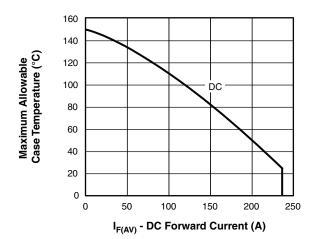


Fig. 4 - Maximum Allowable Case Temperature vs. DC Forward Current (Per Leg)

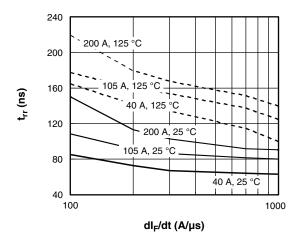


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

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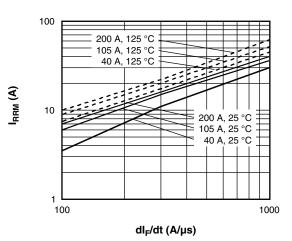
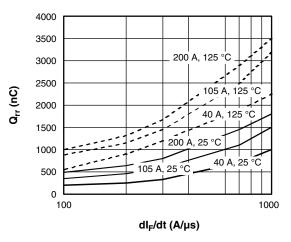
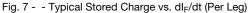


Fig. 6 - - Typical Recovery Current vs. dl_F/dt (Per Leg)





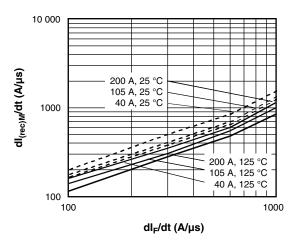


Fig. 8 - - Typical dI_{(rec)M}/dt vs. dI_F/dt (Per Leg)

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VS-HFA210NJ60CPbF www.vishay.com **Vishay Semiconductors** 1 Z_{thJC} - Thermal Response +++++TTT 0.1 D = 0.50 `D = 0.33 0.01 # D = 0.25D = 0.17 Single pulse D = 0.08 (thermal response) 11111 0.001 0.001 0.1 0.00001 0.0001 0.01 10 1

t₁ - Rectangular Pulse Duration (s)

Fig. 9 - - Maximum Thermal Impedance ZthJC Characteristics (Per Leg)

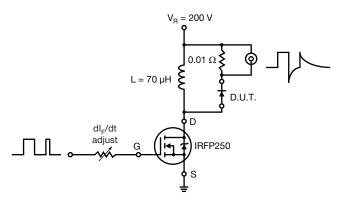
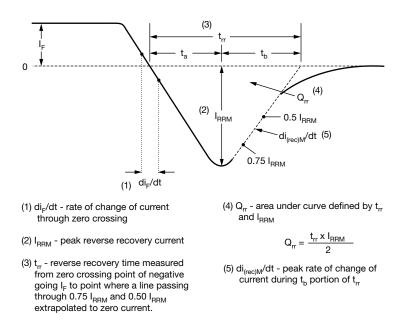
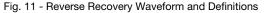


Fig. 10 - - Reverse Recovery Parameter Test Circuit





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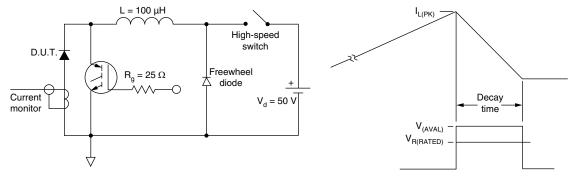
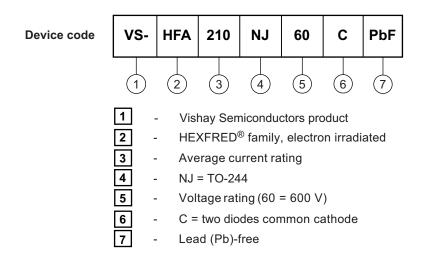


Fig. 12 - Avalanche Test Circuit and Waveforms

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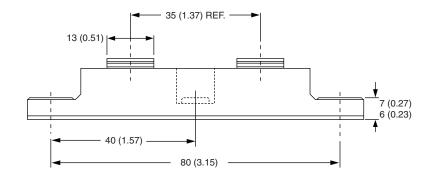


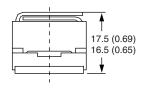


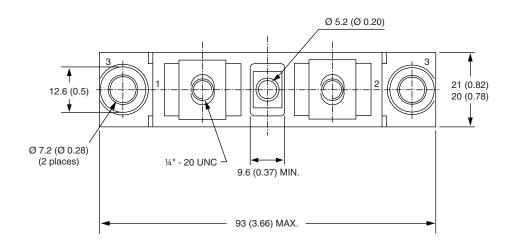
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TO-244

DIMENSIONS in millimeters (inches)









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